Title (en)
REWORKABLE COMPOSITION OF OXIRANE(S) OR THIIRANE(S)-CONTAINING RESIN AND CURING AGENT

Title (de)
WIEDERVERARBEITBARE ZUSAMMENSETZUNGEN BESTEHEND AUS EINEM OXIRAN- ODER THIIRAN ENTHALTENDEN RESIN UND EINEM VERNETZUNGSMITTEL

Title (fr)
COMPOSITION REMANIABLE DE RESINE A BASE D'OXIRANES OU DE THIIRANES ET DURCISSEUR

Publication
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Application
EP 01920494 A 20010327

Priority
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Abstract (en)
[origin: WO0174798A1] A composition useful as underfill sealant for the connection of a semiconductor device to a circuit board is reworkable for more easy separation from the semiconductor device and comprises a curable resin having at least one oxirane or thiirane linkage substituted on at least three of the oxirane or thiirane carbon atoms with an alkyl, alkenyl or aryl substituent along with a curing agent selected from anhydrides, amines, amides, imidazoles, and combinations thereof.

IPC 1-7
C07D 301/14; C08G 59/18; C08L 63/00; C08G 59/20; C08G 59/34; H01L 21/56

IPC 8 full level
C07D 301/14 (2006.01); **C07D 303/28** (2006.01); **C07D 493/08** (2006.01); **C08G 59/18** (2006.01); **C08G 59/20** (2006.01); **C08G 75/08** (2006.01); **C08L 63/00** (2006.01); **H01L 21/56** (2006.01); **H01L 21/60** (2006.01)

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